



Telink

Telink Semiconductor (Shanghai) CO., LTD  
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## Composition Table

To: TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.

From: HuaTian Technology (Xi An) Co.,Ltd

Product Name: TLSR8355F128ET24

Weight(Unit): 37.0000 mg

Date: 2023/10/17

	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	<a href="#">1.5440</a>	Silicon	7440-21-3	1.5440	100.00%	<a href="#">4.17%</a>	1000000
Die2	GD Die	SMIC BJ	<a href="#">0.2760</a>	Silicon	7440-21-3	0.2760	100.00%	<a href="#">0.75%</a>	1000000
Lead Frame	A194	Tianshui Huayang	<a href="#">10.2000</a>					<a href="#">52.45%</a>	
				Cu	7440-50-8	9.8430	96.50%	26.60%	965000
				Fe	7439-89-6	0.2346	2.30%	0.63%	23000
				P	7723-14-0	0.0153	0.15%	0.04%	1500
				Zn	7440-66-6	0.0204	0.20%	0.06%	2000
				Pb	7439-92-1	0.0005	0.01%	0.00%	50
				Ag	7440-22-4	0.0862	0.85%	0.23%	8450
DAF	ATB-120U	Henkel	<a href="#">0.9200</a>	Modified Epoxy Resin	Proprietary	0.6072	66.0%	<a href="#">0.06%</a>	660000
				Phenol, polymer with					
				3a,4,7,7a-tetrahydro-4,7- methano-1H-indene, glycidyl ether	119345-05-0	0.2116	23.0%	0.57%	230000
				Reaction product: bisphenol- F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700) (old)	9003-36-5	0.0460	5.0%	0.12%	50000
				Aromatic polyamine Epoxy Resin	Proprietary Proprietary	0.0460 0.0092	5.0% 1.0%	0.12% 0.02%	50000 10000
Epoxy	L1-403NCA	LEGEND	<a href="#">0.9200</a>	Diethylene glycol monoethyl ether acetate	112-15-2	0.0920	10.00%	<a href="#">0.74%</a>	100000
				Silica	15468-32-3	0.5520	60.00%	1.49%	600000
				Acylate resin	Proprietary	0.1380	15.00%	0.37%	150000
				Epoxy resin	Proprietary	0.1288	14.00%	0.35%	140000
				Peroxide	Proprietary	0.0092	1.00%	0.02%	10000
Wire	R2SP	乐金	<a href="#">1.8200</a>	Silver:Wire	7440-22-4	1.7288	94.9900%	<a href="#">4.67%</a>	949900
				Gold	7440-57-5	0.0091	0.5000%	0.02%	5000
				Palladium	7440-05-3	0.0819	4.5000%	0.22%	45000
				Platinum	7440-6-4	0.0002	0.0100%	0.00%	100
Mold Compound	CEL-9240HF	RESONAC Materials	<a href="#">19.5000</a>					<a href="#">43%</a>	
				Epoxy Resin 1	Trade secret	0.0975	0.50%	0.26%	5000
				Epoxy Resin 2	Trade secret	0.0975	0.50%	0.26%	5000
				Epoxy Resin 3	Trade secret	0.0975	0.50%	0.26%	5000
				Hardener	Trade secret	0.3900	2.00%	1.05%	20000
				Catalyst	Trade secret	0.0020	0.01%	0.01%	100
				Carbon black	1333-86-4	0.0390	0.20%	0.11%	2000
				Amorphous silica1	60676-86-0	17.3141	88.79%	46.79%	887900
				Amorphous silica2	7631-86-9	1.4625	7.50%	3.95%	75000
Plating	TIN	AISEN	<a href="#">1.8200</a>	Tin	7440-31-5	1.8198	99.99%	<a href="#">2.07%</a>	999900
				Others	Trade Secret	0.0002	0.01%	0.00%	100
Total			<a href="#">37.0000</a>			<a href="#">37.0000</a>	<a href="#">100%</a>	<a href="#">1000000</a>	

保存年限：三年  
QRA-051-A1  
保存单位：QRA

文件编号：TFM-